



## Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-03-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

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**Legal Statement**

Supplier Acceptance \* true Legal Declaration \* Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDK7*0124BH6	B	BO2A	2020-03-10
Amount	UoM	Unit type	ST ECOPACK Grade	
130	mg	Each	ECOPACK® 3	
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6 x 3.9	14	gull wing	
Comment	K7 SO 14 .15 TO JEDEC MS-012; MDF is valid for LM224D			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
,			,	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				NO
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CDK7*0124BH6				6000000.0	1000001.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.292	mg	supplier	die	Silicon(Si)	7440-21-3		1.269	mg	982198	9762
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.011	mg	8514	85
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.005	mg	3870	38
				supplier	passivation	Silicon oxide	7631-86-9		0.007	mg	5418	54
				supplier	alloy & coating	Copper(Cu)	7440-50-8		33.885	mg	926351	260654
Leadframe	M-004 Copper and its alloys	36.579	mg	supplier	alloy & coating	Iron(Fe)	7439-89-6		0.797	mg	21788	6131
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.048	mg	1312	369
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.042	mg	1148	323
				supplier	alloy & coating	Silver (Ag)	7440-22-4		1.807	mg	49400	13900
				supplier	glue	Silver(Ag)	7440-22-4		0.255	mg	876289	1962
Die attach	M-015 Other organic materials	0.291	mg	supplier	glue	Isobornyl methacrylate	7534-94-3		0.015	mg	51546	115
				supplier	glue	Isobornyl acrylate	5888-33-5		0.015	mg	51546	115
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.006	mg	20619	46
				supplier	wire	Copper(Cu)	7440-50-8		0.083	mg	1000000	638
Bonding wires	M-004 Copper and its alloys	0.083	mg	supplier	wire	Copper(Cu)	7440-50-8		0.083	mg	1000000	638
				supplier	mold compound	Silica vitreous	60676-86-0		78.370	mg	865996	602846
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		6.787	mg	74997	52208
				supplier	mold compound	Phenol resin	26834-02-6		4.525	mg	50002	34808
				supplier	mold compound	Carbon black	1333-86-4		0.453	mg	5006	3485
Encapsulation	M-011 Other inorganic materials	90.497	mg	supplier	mold compound	Bismuth compound	7440-69-9		0.362	mg	4000	2785
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.258	mg	1000000	9677
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.258	mg	1000000	9677